

UNITED STATES PATENT AND TRADEMARK OFFICE

BEFORE THE PATENT TRIAL AND APPEAL BOARD

APPLE INC.,
Petitioner

v.

IMBERATEK, LLC,
Patent Owner

Case IPR2025-00576
Patent 7,732,909

PETITIONER'S UPDATED LIST OF EXHIBITS

LIST OF EXHIBITS

APPLE-1001	U.S. Patent No. 7,732,909
APPLE-1002	U.S. Patent No. 7,732,909 File History
APPLE-1003	Declaration of Dr. Dean Neikirk
APPLE-1004	Certified Translation of JP Application Publication 2001-339165A (“Sakamoto”)
APPLE-1005	U.S. Patent Application Publication No. 2002/0175402 (“McCormack”)
APPLE-1006	U.S. Patent No. 6,489,685 (“Asahi”)
APPLE-1007	U.S. Patent Application Publication No. 2001/0030059 (“Sugaya”)
APPLE-1008	U.S. Patent Application Publication No. 2002/0020898 (“Vu”)
APPLE-1009	RESERVED
APPLE-1010	RESERVED
APPLE-1011	Certified Translation of JP Patent No. 3207174 (“Hayashi”)
APPLE-1012	Certified Translation of JP Patent Application Publication No. 2002-016327 (“Eiji”)
APPLE-1013	U.S. Patent No. 6,335,571 (“Capote”)
APPLE-1014	U.S. Patent No. 6,297,551 (“Dudderar”)
APPLE-1015	U.S. Patent No. 6,404,052 (“Kurita”)
APPLE-1016	Certified Translation of JP Patent Application Publication No. 2001-068624A (“Imoto”)
APPLE-1017	Certified Translation of PCT Publication No. WO 00/09623 (“Watanabe”)

APPLE-1018	U.S. Patent No. 4,179,802 (“Joshi”)
APPLE-1019	U.S. Patent No. 5,608,262 (“Degani”)
APPLE-1020	U.S. Patent No. 5,321,210 (“Kimbara”)
APPLE-1021	U.S. Patent No. 5,146,674 (“Frankeny”)
APPLE-1022	JP Patent Application Publication No. 2001-339165A (“Sakamoto”)
APPLE-1023	JP Patent No. 3207174 (“Hayashi”)
APPLE-1024	JP Patent Application Publication No. 2002-016327 (“Eiji”)
APPLE-1025	JP Patent Application Publication No. 2001-068624A (“Imoto”)
APPLE-1026	PCT Publication No. WO 00/09623 (“Watanabe”)
APPLE-1027	Certified Translation of JP Patent Application Publication No. 2001-156457 (“Takayama”)
APPLE-1028	JP Patent Application Publication No. 2001-156457 (“Takayama”)
APPLE-1029	U.S. Patent No. 5,745,984 (“Cole”)
APPLE-1030	R. Aschenbrenner, A. Ostmann, U. Beutler, J. Simon and H. Reichl, “Electroless nickel/copper plating as a new bump metallization,” in IEEE Transactions on Components, Packaging, and Manufacturing Technology: Part B, vol. 18, no. 2, pp. 334-338, May 1995, doi: 10.1109/96.386270
APPLE-1031	W. W. Flack, Ha-Ai Nguyen, E. Capsuto and C. McEwen, “Characterization of a thick copper pillar bump process,” 2007 12th International Symposium on Advanced Packaging Materials: Processes, Properties, and Interfaces, San Jose, CA, USA, 2007, pp. 208-213.
APPLE-1032	Xiang Dai, M. V. Brillhart, M. Roesch and P. S. Ho, “Adhesion and toughening mechanisms at underfill interfaces for flip-chip-on-organic-substrate packaging,” in

IEEE Transactions on Components and Packaging
Technologies, vol. 23, no. 1, pp. 117-127, March 2000

- APPLE-1033 D. Suryanarayana, T. Y. Wu and J. A. Varcoe,
“Encapsulants used in flip-chip packages,” in IEEE
Transactions on Components, Hybrids, and Manufacturing
Technology, vol. 16, no. 8, pp. 858-862, Dec. 1993
- APPLE-1034 U.S. Patent Application Publication No. 2001/0033889
 (“Bhatt”)
- APPLE-1035 Apple Inc. Stipulation Letter

Respectfully submitted,

Dated: April 29, 2025

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CERTIFICATE OF SERVICE

Pursuant to 37 CFR § 42.6(e), the undersigned certifies that on April 29, 2025, a complete and entire copy of this Petitioner's Updated List of Exhibits and its supporting exhibit were provided via email to the Patent Owner by serving the correspondence of record as follows:

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